

CLAIMS

1. An apparatus for processing a substrate with a fluid meniscus to be applied to a surface of the substrate, comprising:
 - 5 a docking surface configured to be placed adjacent to an edge of the substrate, the docking surface being about in the same plane as the substrate, and providing a transition interface to allow the fluid meniscus to enter and exit the surface of the substrate.
2. An apparatus for processing a substrate as recited in claim 1, wherein the
 - 10 docking surface defines a docking station for the fluid meniscus.
3. An apparatus for processing a substrate as recited in claim 2, further comprising,
 - 15 a coupon magazine for holding the docking station that includes the docking surface.
4. An apparatus for processing a substrate as recited in claim 1, wherein the docking surface has a radial contour that matches a radial contour of the substrate.
- 20 5. An apparatus for use in processing a substrate, comprising:
 - a coupon magazine configured to hold a docking station for a proximity head, the coupon magazine being configured so the docking station is held in place adjacent to an edge of the substrate.

6. An apparatus for use in processing a substrate as recited in claim 5, wherein the docking station is defined by a docking surface that provides a transition interface for a fluid meniscus of the proximity head.

5 7. An apparatus for use in processing a substrate as recited in claim 5, wherein the coupon magazine includes a top portion and a bottom portion.

8. An apparatus for use in processing a substrate as recited in claim 7, wherein the docking station is held between the top portion and the bottom portion.

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9. An apparatus for use in processing a substrate as recited in claim 5, wherein the docking station is a quartz material.

10. An apparatus for use in processing a substrate as recited in claim 5,
15 wherein the docking station is a hydrophilic material.

11. An apparatus for use in processing a substrate as recited in claim 5, further comprising,

a coupon magazine mount configured to hold the coupon magazine.

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12. An apparatus for use in processing a substrate as recited in claim 5, further comprising,

a leveling mechanism configured to move the docking station to be substantially coplanar with the substrate.

13. An apparatus for use in processing a substrate as recited in claim 12, wherein the leveling mechanism is configured to move the docking station in a vertical plane.

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14. An apparatus for use in processing a substrate as recited in claim 12, wherein the leveling mechanism includes a screw configured to move a ball detent vertically.

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15. An apparatus for use in processing a substrate as recited in claim 5, wherein the coupon magazine includes a sight window.

16. A method for processing a substrate, comprising:

positioning a transition surface substantially coplanar to a substrate surface, the
15 transition surface being adjacent to an edge of the substrate; and

moving a fluid meniscus between the transition surface and the substrate surface.

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17. A method for processing a substrate as recited in claim 16, wherein positioning the transition surface includes leveling the transition surface.

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18. A method for processing a substrate as recited in claim 17, wherein the leveling is accomplished by the leveling mechanism.

19. A method for processing a substrate as recited in claim 16, wherein the transition surface is a hydrophilic material.

20. A method for processing a substrate as recited in claim 16, wherein
5 moving the fluid meniscus between the transition surface and the substrate surface includes one of moving the fluid meniscus onto the transition surface from the substrate surface and moving the fluid meniscus onto the substrate surface from the transition surface.

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